

CM200RL-24NF

HIGH POWER SWITCHING USE

CM200RL-24NF



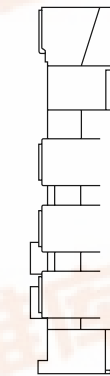
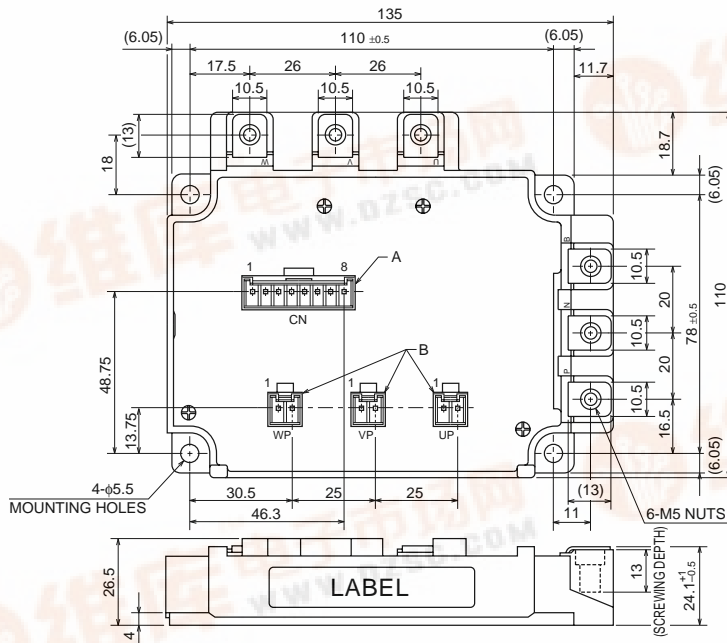
- IC 200A
- VCES 1200V
- Insulated Type
- 7-elements in a pack

APPLICATION

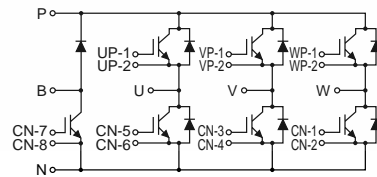
AC drive inverters & Servo controls, etc

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



Housing Type of A and B
(J.S.T.Mfg.Co.Ltd)
A = B8P-VH-FB-B, B = B2P-VH-FB-B



CIRCUIT DIAGRAM



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ABSOLUTE MAXIMUM RATINGS ($T_j = 25^\circ\text{C}$)

INVERTER PART

Symbol	Parameter	Conditions	Ratings	Unit
VCES	Collector-emitter voltage	G-E Short	1200	V
VGES	Gate-emitter voltage	C-E Short	± 20	V
IC	Collector current	DC, $T_c = 72^\circ\text{C}^{*1}$	200	A
ICM		Pulse (Note 2)	400	A
IE (Note 1)	Emitter current		200	A
IEM (Note 1)		Pulse (Note 2)	400	A
PC (Note 3)	Maximum collector dissipation	$T_c = 25^\circ\text{C}$	1160	W

BRAKE PART

Symbol	Parameter	Conditions	Ratings	Unit
VCES	Collector-emitter voltage	G-E Short	1200	V
VGES	Gate-emitter voltage	C-E Short	± 20	V
IC	Collector current	DC, $T_c = 80^\circ\text{C}^{*1}$	100	A
ICM		Pulse (Note 2)	200	A
PC (Note 3)	Maximum collector dissipation	$T_c = 25^\circ\text{C}$	620	W
VRRM	Repetitive peak reverse voltage	Clamp diode part	1200	V
IFM	Forward current	Clamp diode part	100	A

(COMMON RATING)

Symbol	Parameter	Conditions	Ratings	Unit
T_j	Junction temperature		$-40 \sim +150$	$^\circ\text{C}$
T_{stg}	Storage temperature		$-40 \sim +125$	$^\circ\text{C}$
V_{iso}	Isolation voltage	Main Terminal to base plate, AC 1 min.	2500	V
—	Torque strength	Main Terminal M5	2.5 ~ 3.5	N • m
—		Mounting holes M5	2.5 ~ 3.5	N • m
—	Weight	Typical value	750	g

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ELECTRICAL CHARACTERISTICS (T_j = 25°C)

INVERTER PART

Symbol	Parameter	Test conditions	Limits			Unit	
			Min.	Typ.	Max.		
ICES	Collector cutoff current	VCE = VCES, VGE = 0V	—	—	1	mA	
VGE(th)	Gate-emitter threshold voltage	IC = 20mA, VCE = 10V	6	7	8	V	
IGES	Gate leakage current	VGE = VGES, VCE = 0V	—	—	0.5	μA	
VCE(sat)	Collector-emitter saturation voltage	IC = 200A, VGE = 15V	T _j = 25°C	—	2.1	3.1	V
			T _j = 125°C	—	2.4	—	
Cies	Input capacitance	VCE = 10V VGE = 0V	—	—	35	nF	
Co _{es}	Output capacitance		—	—	3	nF	
C _{res}	Reverse transfer capacitance		—	—	0.68	nF	
QG	Total gate charge	VCC = 600V, IC = 200A, VGE = 15V	—	1000	—	nC	
td(on)	Turn-on delay time	VCC = 600V, IC = 200A VGE1 = VGE2 = 15V RG = 1.6Ω, Inductive load switching operation	—	—	130	ns	
tr	Turn-on rise time		—	—	70	ns	
td(off)	Turn-off delay time		—	—	400	ns	
tf	Turn-off fall time		—	—	350	ns	
trr (Note 1)	Reverse recovery time		IE = 200A	—	—	150	ns
Q _{rr} (Note 1)	Reverse recovery charge		—	9	—	μC	
VEC(Note 1)	Emitter-collector voltage	IE = 200A, VGE = 0V	—	—	3.8	V	
R _{th(j-c)Q}	Thermal resistance	IGBT part (1/6 module) ^{*1}	—	—	0.11	°C/W	
R _{th(j-c)R}		FWDi part (1/6 module) ^{*1}	—	—	0.17	°C/W	
R _{th(c-f)}	Contact thermal resistance	Case to fin, Thermal compound Applied (1/6 module) ^{*2}	—	0.051	—	°C/W	
RG	External gate resistance		1.6	—	21	Ω	

BRAKE PART

Symbol	Parameter	Test conditions	Limits			Unit	
			Min.	Typ.	Max.		
ICES	Collector cutoff current	VCE = VCES, VGE = 0V	—	—	1	mA	
VGE(th)	Gate-emitter threshold voltage	IC = 10mA, VCE = 10V	6	7	8	V	
IGES	Gate leakage current	VGE = VGES, VCE = 0V	—	—	0.5	μA	
VCE(sat)	Collector-emitter saturation voltage	IC = 100A, VGE = 15V	T _j = 25°C	—	2.1	3.0	V
			T _j = 125°C	—	2.4	—	
Cies	Input capacitance	VCE = 10V VGE = 0V	—	—	17.5	nF	
Co _{es}	Output capacitance		—	—	1.5	nF	
C _{res}	Reverse transfer capacitance		—	—	0.34	nF	
QG	Total gate charge	VCC = 600V, IC = 100A, VGE = 15V	—	500	—	nC	
VFM	Forward voltage drop	IF = 100A	—	—	3.8	V	
R _{th(j-c)Q}	Thermal resistance	IGBT part ^{*1}	—	—	0.20	°C/W	
R _{th(j-c)R}		Clamp diode part ^{*1}	—	—	0.28	°C/W	
RG	External gate resistance		3.1	—	31	Ω	

*1 : T_c measured point is just under the chips.

If you use this value, R_{th(t-a)} should be measured just under the chips.

*2 : Typical value is measured by using Shin-etsu Silicone "G-746".

Note 1. IE, VEC, trr & Q_{rr} represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

2. Pulse width and repetition rate should be such that the device junction temp. (T_j) does not exceed T_{jmax} rating.

3. Junction temperature (T_j) should not increase beyond 150°C.

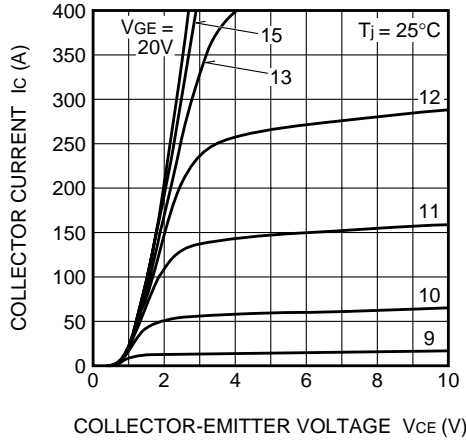
4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

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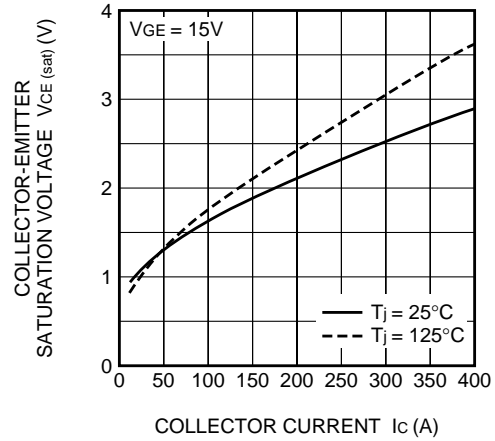
HIGH POWER SWITCHING USE

PERFORMANCE CURVES

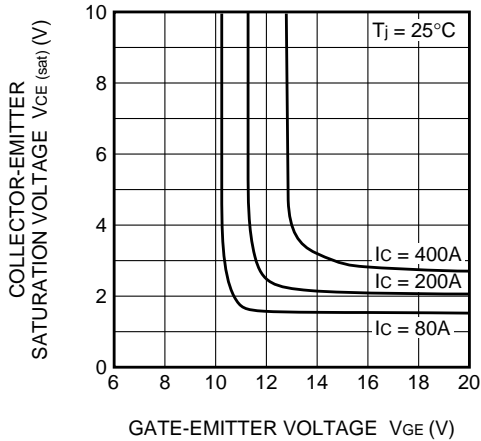
OUTPUT CHARACTERISTICS (TYPICAL)



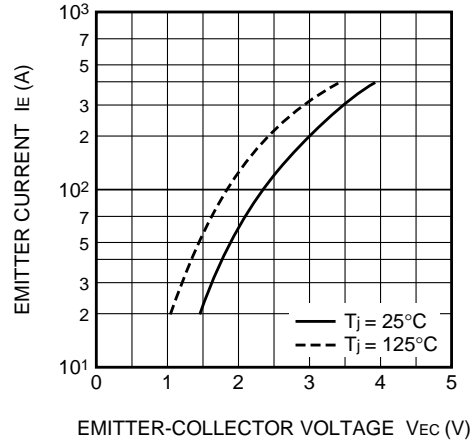
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



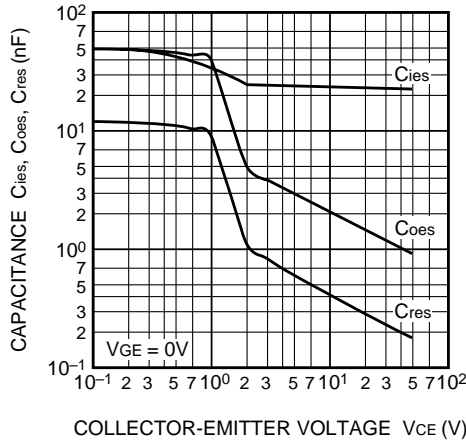
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



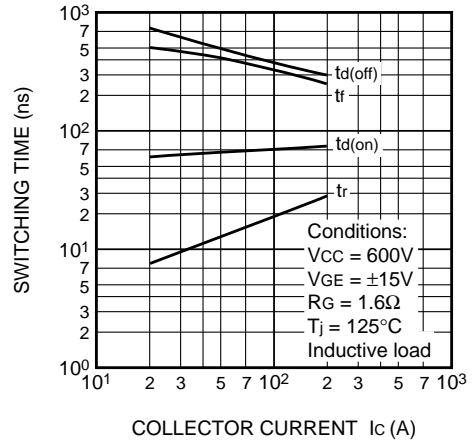
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



CAPACITANCE-Vce CHARACTERISTICS (TYPICAL)



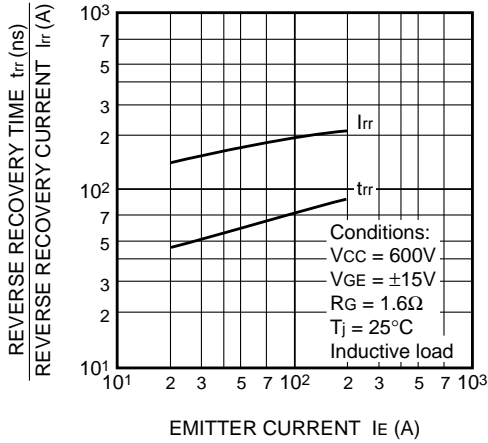
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



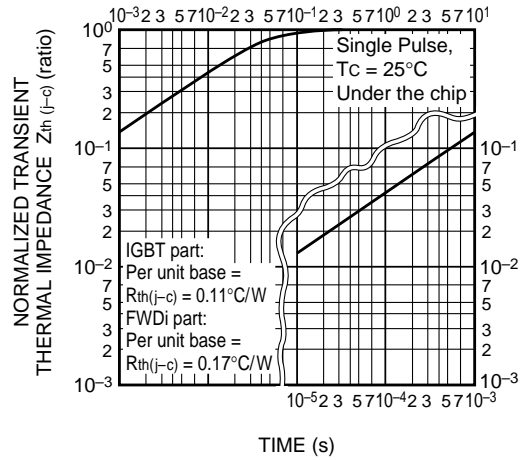
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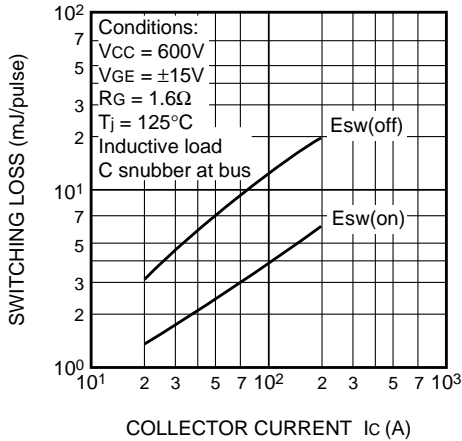
REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



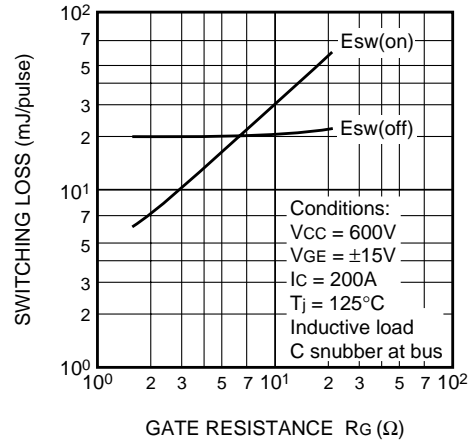
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



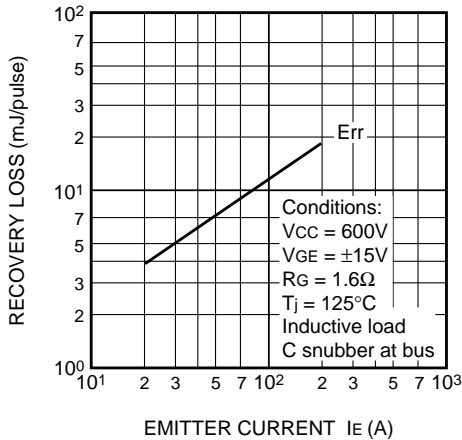
SWITCHING LOSS vs. COLLECTOR CURRENT (TYPICAL)



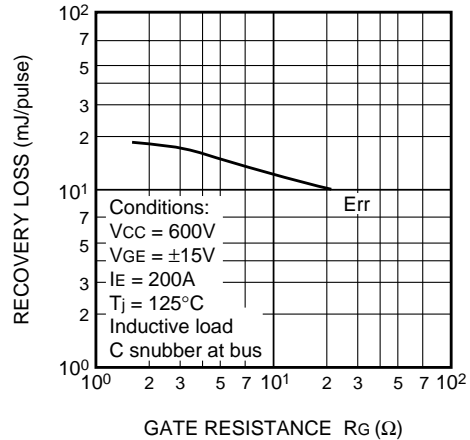
SWITCHING LOSS vs. GATE RESISTANCE (TYPICAL)



RECOVERY LOSS vs. IE (TYPICAL)



RECOVERY LOSS vs. GATE RESISTANCE (TYPICAL)



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